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ABSTRACT OF THE DISCLOSURE

A computing device having an improved enclosure arrangement is disclosed. One aspect of the enclosure pertains to enclosure parts that are structurally bonded together to form a singular composite structure. In one embodiment, structural glue is used to bond at least two unique parts together. Another aspect of the enclosure pertains to enclosure parts that are electrically bonded together to form a singular integrated conductive member. In one embodiment, conductive paste is used to bond at least two unique parts together. The improved enclosure is particularly useful in portable computing devices such as laptop computers.